

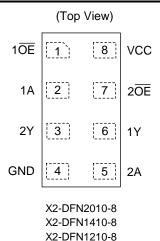


#### **DUAL BUFFER GATE WITH 3-STATE OUTPUTS**

#### **Description**

The 74LVC2G125 is a dual buffer gate with 3-state outputs. The device is designed for operation over a power supply range of 1.65V to 5.5V. The device is fully specified for partial power down applications using  $I_{\text{OFF}}$ . The  $I_{\text{OFF}}$  circuitry disables the output, preventing damaging current backflow when the device is powered down.

#### **Pin Assignments**



#### **Features**

- Wide Supply Voltage Range from 1.65 to 5.5V
- ± 24mA Output Drive at 3.3V
- CMOS Low Power Consumption
- I<sub>OFF</sub> Supports Partial-Power-Down Mode Operation
- Inputs accept up to 5.5V
- Schmitt Trigger Action at all inputs makes the circuit tolerant for slower input rise and fall times. The hysteresis is typically 100mV at V<sub>CC</sub> = 3.0V.
- ESD Protection Exceeds JESD 22
  - 2000-V Human Body Model (A114)
  - Exceeds 1000-V Charged Device Model (C101)
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Applications**

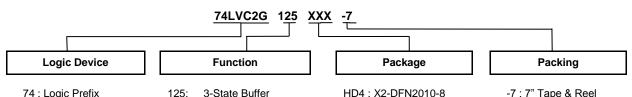
- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products Such as:
  - PCs, Networking, Notebooks, Netbooks, PDAs
  - Tablet Computers, E-readers
  - Computer Peripherals, Hard Drives, CD/DVD ROMs
  - TVs, DVDs, DVRs, Set Top Boxes
  - Cell Phones, Personal Navigation / GPS
  - MP3 Players, Cameras, Video Recorders

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



### Ordering Information (Note 4)



74 : Logic Prefix LVC: 1.65V to 5.5V Logic Family 2G: Dual Gate

3-State Buffer OE - Low

HD4: X2-DFN2010-8 HK3: X2-DFN1410-8 RA3: X2-DFN1210-8

-7: 7" Tape & Reel

	Package Package Package		Package Package		7" Tape and Re	el (Note 6)	
Device	Code	(Note 5)	Size	Quantity	Part Number Suffix		
74LVC2G125HD4-7	HD4	X2-DFN2010-8	1.95mm x 1.0mm x 0.4mm 0.5 mm lead pitch	5,000/Tape & Reel	-7		
74LVC2G125HK3-7	HK3	X2-DFN1410-8	1.35mm x 1.0mm x 0.35mm 0.4 mm lead pitch	5,000/Tape & Reel	-7		
74LVC2G125RA3-7	RA3	X2-DFN1210-8	1.2mm x 1.0mm x 0.35mm 0.3 mm lead pitch	5,000/Tape & Reel	-7		

Notes: 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

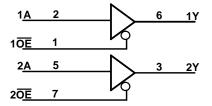
5. Pad layout as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at http://www.diodes.com/package-outlines.html.

6. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.

#### **Pin Descriptions**

Pin Name	Pin No.	Description	
1 OE	1	Output Enable for buffer 1	
1A	2	Data Input	
2Y	3	Data Output	
GND	4	Ground	
2A	5	Data Input	
1Y	6	Data Output	
2 OE	7	Output Enable for buffer 2	
Vcc	8	Supply Voltage	

## **Logic Diagram**



#### **Function Table**

Inp	Output	
ŌĒ	Y	
L	Н	Н
L	L	L
Н	X	Z



## Absolute Maximum Ratings (Notes 7 & 8)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
Vcc	Supply Voltage	-0.5 to +6.5	V
VI	Input Voltage	-0.5 to +6.5	V
Vo	Output Voltage -Active Mode	-0.5 to V <sub>CC</sub> +0.5	V
Vo	Output Voltage Power Down Mode	-0.5 to +6.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> <0	-50	mA
I <sub>OK</sub>	Output Clamp Current (Vo < 0 OR Vo > Vcc )	±50	mA
lo	Continuous Output Current (Vo = 0 to Vcc)	±50	mA
Icc	Continuous Current Through V <sub>CC</sub>	100	mA
I <sub>GND</sub>	Continuous Current Through GND	-100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C

Notes:

## **Recommended Operating Conditions** (Note 9)

Symbol	Pa	Min	Max	Unit		
.,	On and the self-the sec	Operating	1.65	5.5	.,	
V <sub>CC</sub>	Operating Voltage	Data Retention Only	1.5	_	V	
VI	Input Voltage		0	5.5	V	
\/-	Output Voltage Active Mode		0	Vcc	V	
Vo	Output Voltage Power-Down Mode		0	5.5	V	
	I <sub>OH</sub> High-Level Output Current	V <sub>CC</sub> = 1.65V	_	-4		
		V <sub>CC</sub> = 2.3V	_	-8	mA	
		V <sub>CC</sub> = 2.7V	_	-12		
IOH		V 2.0V	_	-16		
		$V_{CC} = 3.0V$		-24		
		$V_{CC} = 4.5V$	_	-32		
		V <sub>CC</sub> = 1.65V	_	4		
		V <sub>CC</sub> = 2.3V	_	8		
I.e.	Low-Level Output Current	V <sub>CC</sub> = 2.7V	_	12	mΛ	
loL	Low-Level Output Current	V 0.0V	_	16	mA	
		$V_{CC} = 3.0V$	_	24		
		V <sub>CC</sub> = 4.5V	_	32		
A+/A>/	land Transition Disc or Fall Date	V <sub>CC</sub> = 1.65V to 2.7V	_	20		
Δt/ΔV	Input Transition Rise or Fall Rate	V <sub>CC</sub> = 2.7V to 5.5V	_	10	ns/V	
T <sub>A</sub>	Operating Fr	ee-Air Temperature	-40	+125	°C	

Note: 9. Unused inputs should be held at  $V_{CC}$  or Ground.

<sup>7.</sup> Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

<sup>8.</sup> Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.



## **Electrical Characteristics** (All typical values are at $T_A = +25$ °C)

		T 10 111	.,	-40	°C to +8	5°C	-40°C to	+125°C	
Symbol	Parameter	Test Conditions	V <sub>cc</sub>	Min	Тур.	Max	Min	Max	Unit
			V <sub>CC</sub> = 1.65V to 1.95V	0.65 x V <sub>CC</sub>	_	_	0.65 x V <sub>CC</sub>	_	
	V <sub>IH</sub> High-Level Input Voltage		V <sub>CC</sub> = 2.3V to 2.7V	1.7	_	_	1.7	_	
$V_{IH}$		_	V <sub>CC</sub> = 2.7V to 3.6V	2.0	_	_	2.0	_	٧
			V <sub>CC</sub> = 4.5V to 5.5V	0.7 x V <sub>CC</sub>	_	_	0.7 x V <sub>CC</sub>	_	
			V <sub>CC</sub> = 1.65V to 1.95V	_	_	0.35 x V <sub>CC</sub>	_	0.35 x V <sub>CC</sub>	
.,	Low-Level		V <sub>CC</sub> = 2.3V to 2.7V	_	_	0.7	_	0.7	l
$V_{IL}$	Input Voltage	_	V <sub>CC</sub> = 2.7V to 3.6V	_	_	0.8	_	0.8	V
			$V_{CC} = 4.5 \text{V to } 5.5 \text{V}$	_	_	0.3 x V <sub>CC</sub>	_	0.3 x V <sub>CC</sub>	
		I <sub>OH</sub> = -100μA	1.65V to 5.5V	V <sub>CC</sub> - 0.1	Vcc	_	V <sub>CC</sub> - 0.1	_	
		I <sub>OH</sub> = -4mA	1.65V	1.2	1.53	_	0.95	_	
	High-Level	I <sub>OH</sub> = -8mA	2.3V	1.9	2.13	_	1.7	_	
$V_{OH}$	Output	I <sub>OH</sub> = -12mA	2.7	2.2	2.5	_	1.9	_	V
	Voltage	I <sub>OH</sub> = -16mA	2) /	2.4	2.7	_	2.2	_	
		I <sub>OH</sub> = -24mA	3V	2.3	2.6	_	2.0	_	
		I <sub>OH</sub> = -32mA	4.5V	3.8	4.1	_	3.4	_	
		I <sub>OL</sub> = 100μA	1.65V to 5.5V	_	0	0.1	_	0.1	
		I <sub>OL</sub> = 4mA	1.65V	_	0.08	0.45	_	0.7	
	Low-Level	$I_{OL} = 8mA$	2.3V	_	0.14	0.3	_	0.45	
$V_{OL}$	Output Voltage	$I_{OL} = 12mA$	2.7V	_	0.19	0.4	_	0.6	V
		I <sub>OL</sub> = 16mA	0) /	_	0.25	0.4	_	0.6	
		$I_{OL} = 24mA$	3V	_	0.37	0.55	_	0.8	
		$I_{OL} = 32mA$	4.5V	_	0.43	0.55	_	0.8	
II	Input Current	V <sub>I</sub> = 5.5V or GND	0V to 5.5V	_	± 0.1	±5	_	± 20	μΑ
l <sub>OZ</sub>	Z-State Leakage Current	$V_I = V_{IH}$ or $V_{IL}$ $V_O = 5.5V$ or GND	3.6V	_	± 0.1	± 10	_	±20	μА
l <sub>OFF</sub>	Power Down Leakage Current	$V_1 \text{ or } V_0 = 5.5V$	0V	_	± 0.1	±10	_	±20	μА
Icc	Supply Current	$V_1 = 5.5V$ or GND $I_0=0A$	1.65V to 5.5V	_	0.1	10	_	40	μΑ
ΔI <sub>CC</sub>	Additional Supply Current	One input at V <sub>CC</sub> –0.6V Other inputs at V <sub>CC</sub> or GND	2.3V to 5.5V	_	5	500	_	5,000	μА
Cı	Input Capacitance	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3V	_	2.5	_	_	_	pF



## **Operating Characteristics**

	Parameter	Test Conditions	V <sub>CC</sub> = 1.8V Typ.	V <sub>CC</sub> = 2.5V Typ.	V <sub>CC</sub> = 3.3V Typ.	V <sub>cc</sub> = 5V Typ.	Unit
	Power Dissipation	f = 10MHz output enabled	17	17	17	17	pF
$C_{pd}$	Capacitance	f = 10MHz output disabled	5	5	5	5	pF

## **Package Characteristics**

Symbol	Parameter	Package	Test Conditions	Min	Тур.	Max	Unit	
	θ <sub>JA</sub> Thermal Resistance Junction- to-Ambient		X2-DFN2010-8		_	313	_	
$\theta_{JA}$		X2-DFN1410-8	(Note 10)	_	321	_	°C/W	
		X2-DFN1210-8		_	395	_		
	- 15	X2-DFN2010-8		_	145	_		
θ <sub>JC</sub> Therr to-Ca	Thermal Resistance Junction-	X2-DFN1410-8	(Note 10)	_	166	_	°C/W	
	10-Case	X2-DFN1210-8		_	236	_		

Note: 10. Test condition for each package type: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

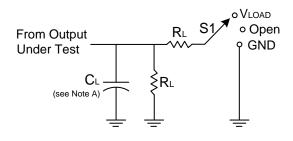
## **Switching Characteristics**

Typical Values at  $T_A = +25$ °C and nominal voltages 1.8V, 2.5V, 2.7V, 3.3V, and 5.0V. See Figure 1.

D	From	То	v	T <sub>A</sub> =	= -40°C to +8	85°C	T <sub>A</sub> = -40°C	to +125°C	1111					
Parameter	Input	Output	V <sub>CC</sub>	Min	Тур	Max	Min	Max	Unit					
				1.8V ± 0.15V	1.0	3.7	9.1	1.0	11.4					
			2.5V ± 0.2V	0.5	2.5	4.8	0.5	6.0						
t <sub>pd</sub>	Α	Y	2.7V	1.0	2.7	4.8	1.0	6.0	ns					
			3.3V ± 0.3V	0.5	2.3	4.4	0.5	5.5						
			5.0V ± 0.5V	0.5	1.9	3.7	0.5	4.6						
	ŌĒ				1.8V ± 0.15V	1.5	4.3	9.9	1.5	12.4				
			2.5V ± 0.2V	1.0	2.8	5.6	1.0	7.0						
t <sub>en</sub>		OE	ŌE	OE	Υ	Υ	Υ	Υ	2.7V	1.5	3.3	5.7	1.5	7.1
			3.3V ± 0.3V	0.5	2.4	5.0	0.5	5.9						
			5.0V ± 0.5V	0.5	2.0	3.8	0.5	4.8						
			1.8V ± 0.15V	1.0	3.5	11.6	1.0	14.1						
			2.5V ± 0.2V	0.5	1.8	5.8	0.5	7.6						
t <sub>dis</sub>	ŌĒ	ŌE Y	2.7V	1.0	2.7	4.8	1.0	6.2	ns					
			3.3V ± 0.3V	1.0	2.7	4.6	1.0	5.9						
			5.0V ± 0.5V	0.5	1.8	3.4	0.5	4.6						



#### **Parameter Measurement Information**

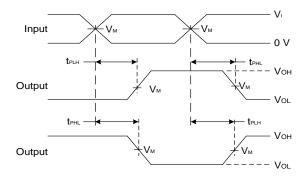


TEST	S1
tplH/tpHL	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	$V_{LOAD}$
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

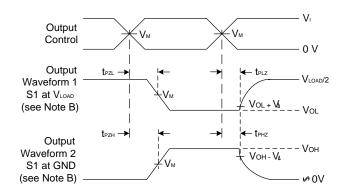
V	Inputs					-	
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	VM VLOAD		CL	$R_L$	<b>V</b> Δ
1.8V±0.15V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	30pF	1kΩ	0.15V
2.5V±0.2V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	30pF	500Ω	0.15V
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.5V	V <sub>CC</sub>	≤2.5ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	50pF	500Ω	0.3V



**Voltage Waveform Pulse Duration** 



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs



Voltage Waveform Enable and Disable Times

Low and High Level Enabling

Figure 1. Load Circuit and Voltage Waveforms

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 10MHz.

C. Inputs are measured separately one transition per measurement.

D.  $t_{\text{PLZ}}$  and  $t_{\text{PHZ}}$  are the same as  $t_{\text{dis.}}$ 

E. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en.</sub>

F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd.}$ 



## **Marking Information**

(Top View)

<u>XX</u> <u>Y W X</u> XX: Identification Code

Y: Year: 0~9

<u>W</u>: Week: A~Z: 1~26 week; a~z: 27~52 week; z represents 52 and 53 week

X: Internal Code

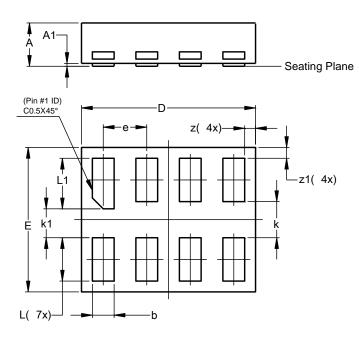
Part Number	Package	Identification Code
74LVC2G125HD4-7	X2-DFN2010-8	9U
74LVC2G125HK3-7	X2-DFN1410-8	9V
74LVC2G125RA3-7	X2-DFN1210-8	9W



### X2-DFN1210-8 Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1210-8

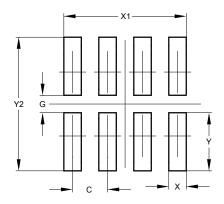


X2-DFN1210-8			
Dim	Min	Max	Тур
Α	-	0.35	0.30
A1	0	0.03	0.02
b	0.10	0.20	0.15
D	1.15	1.25	1.20
Е	0.95	1.05	1.00
е	-	-	0.30
k	-	-	0.25
k1	-	-	0.20
L	0.25	0.35	0.30
L1	0.30	0.40	0.35
z	0.050	0.100	0.075
<b>z</b> 1	0.050	0.100	0.075
All Dimensions in mm			

### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1210-8



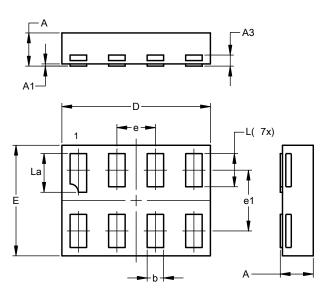
Dimensions	Value (in mm)	
С	0.300	
G	0.150	
Х	0.150	
X1	1.050	
Y	0.500	
Y1	1.150	



## X2-DFN1410-8 Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1410-8

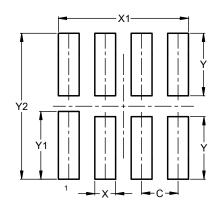


X2-DFN1410-8				
Dim	Min	Max	Тур	
Α	0.30	0.35	0.33	
A1	0.00	0.03	0.02	
A3			0.10	
b	0.12	0.20	0.15	
D	1.30	1.40	1.35	
Е	0.95	1.05	1.00	
е			0.35	
e1			0.55	
L	0.27	0.35	0.30	
L1	0.32	0.40	0.35	
All Dimensions in mm				

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1410-8



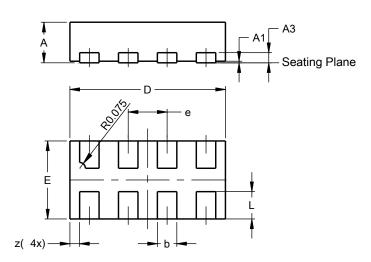
Dimensions	Value	
HILIEUSIOUS	(in mm)	
С	0.350	
Х	0.200	
X1	1.250	
Y	0.600	
Y1	0.650	
Y2	1.400	



## X2-DFN2010-8 Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN2010-8

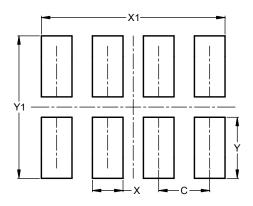


X2-DFN2010-8			
Dim	Min	Max	Тур
Α		0.40	
A1	0.00	0.05	0.02
A3			0.13
b	0.20	0.30	0.25
D	1.950	2.05	2.00
Е	0.95	1.05	1.00
е			0.50
Ĺ	0.30	0.40	0.35
Z			0.125
All Dimensions in mm			

#### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN2010-8



Dimensions	Value	
Dillielisions	(in mm)	
С	0.500	
Х	0.300	
X1	1.800	
Y	0.600	
Y1	1.400	



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NLV37WZ17USG 74HCT126T14-13 74VHC9126FT(BJ) RHRXH162244K1 74AUP1G34FW5-7 74AUP1G07FW5-7 74LVC1G126FW4-7

74LVC2G126RA3-7 74LVCE1G125FZ4-7 74AUP1G126FW5-7 54FCT240TLB NLX3G16DMUTCG NLX2G06AMUTCG

LE87100NQCT LE87285NQC LE87290YQC LE87290YQCT 74AUP1G125FW5-7 NLU2G16CMUTCG MC74LCX244MN2TWG

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T13 MC100EP17MNG MC74HCT365ADR2G MC74LCX244ADTR2G NL27WZ126US NL37WZ16US NLU1G07MUTCG

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